

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L20	2	("6429096").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/09/11 09:46
L21	2	("6627988").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/09/11 09:48
L22	10	("20010009302" "5229643" "5554887" "5903052" "5920117" "6184580" "6219243" "6259156"). PN. OR ("6627988").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/09/11 09:47
L23	2	("6376769").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/09/11 09:58
L24	91	("3555364" "4734825" "5043794" "5148265" "5172303" "5192716" "5286926" "5347159" "5367764" "5371654" "5375041" "5386341" "5394303" "5473119" "5483421" "5548091" "5558928" "5570504" "5583321" "5665473" "5672548" "5682061" "5685885" "5686699" "5734555" "5777379" "5783870" "5794330" "5798564" "5801439" "5848467" "5861666" "5875545" "5901041" "5915170" "5926369" "5929517" "5943213" "5950304" "6108210").PN. OR ("6376769"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/09/11 09:51
L25	2	("6673651").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/09/11 09:59
L26	15	("5239198" "5668405" "5866949" "5880590" "5895965" "5925934" "6031292" "6083776" "6166443" "6201302" "6229215" "6259154" "6326696" "6404049").PN. OR ("6673651").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/09/11 10:03

EAST Search History

L27	2	("6673651").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/09/11 10:03
L28	2	"20020070458"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/11 10:03
L29	75	("4413308" "4581680" "4641222" "4707657" "5077598" "5137461" "5148266" "5258330" "5352926" "5367435" "5369551" "5414298" "5435732" "5450290" "5451720" "5453580" "5473120" "5477082" "5477933" "5483421" "5491303" "5509815" "5586010" "5598033" "5690270" "5700549" "5738531" "5800184" "5829988" "5880890").PN. OR ("6050832"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/09/11 10:33
L31	55	@ad<="20040330" and "flexible" with interposer with solder with ball	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/11 10:42
L32	48	@ad<="20040330" and "flexible" with interposer with "solder ball"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/11 11:03
L33	25	@ad<="20040330" and "flexible interposer" same "solder ball"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/11 11:49
L34	2	("6830463").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/09/11 11:49
S1	2	"20040201096"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 09:03
S2	2289	@ad<="20040330" and (257/678). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 09:13

EAST Search History

S3	2099	@ad<="20040330" and (257/697-698).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 09:04
S4	1585	@ad<="20040330" and (257/700).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 09:04
S5	1913	@ad<="20040330" and (257/784).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 09:38
S6	1756	@ad<="20040330" and (257/786).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 09:07
S7	10	@ad<="20040330" and 'flexible' same 'wiring circuit' and 'solder ball' and 'printed circuit board'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 09:16
S8	1	"6580031".PN.	USPAT; USOCR	OR	ON	2005/10/20 09:10
S9	1	"6580031".PN.	USPAT; USOCR	OR	ON	2005/10/20 09:11
S10	6144	@ad<="20040330" and (361/749-750).ccls. or (361/760).ccls. or (361/792).ccls. or (361/795).ccls. or (257/686).ccls. or (257/685).ccls. or (257/688).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 09:16
S11	21	@ad<="20040330" and 'flexible' same 'wiring substrate' and 'solder ball' and 'printed circuit board'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 09:20
S12	864	S10 and 'flexible' with 'substrate'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 09:17
S13	235	@ad<="20040330" and 'wiring substrate' and 'solder ball' and 'printed circuit board'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/23 11:38
S14	1	"6285081".PN.	USPAT; USOCR	OR	ON	2005/10/20 09:30
S15	1	"6181569".PN.	USPAT; USOCR	OR	ON	2005/10/20 09:30

EAST Search History

S16	1	"6114187".PN.	USPAT; USOCR	OR	ON	2005/10/20 09:31
S17	1	"6005292".PN.	USPAT; USOCR	OR	ON	2005/10/20 09:31
S18	1	"5900738".PN.	USPAT; USOCR	OR	ON	2005/10/20 09:33
S19	1	"5414371".PN.	USPAT; USOCR	OR	ON	2005/10/20 09:33
S20	1	"5086337".PN.	USPAT; USOCR	OR	ON	2005/10/20 09:33
S21	3938	@ad<="20040330" and (257/773-774).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 09:38
S22	931	@ad<="20040330" and ('wiring board' or 'wiring tape') and 'solder ball' and ('printed circuit board' or 'PCB')	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 10:15
S23	6	@ad<="20040330" and ('wiring board' or 'wiring tape') and 'solder ball' and ('printed circuit board' or 'PCB') and 'metal stud'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 10:15
S24	10	@ad<="20040330" and ('wiring board' or 'wiring tape') and 'solder ball' and ('printed circuit board' or 'PCB') and 'metal' with 'stud'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 10:16
S25	8	@ad<="20040330" and ('wiring board' or 'wiring tape') and 'solder ball' and ('printed circuit board' or 'PCB') and 'metal' with 'plug'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 10:16
S26	180	@ad<="20040330" and ('wiring board' or 'wiring tape') and 'solder ball' and ('printed circuit board' or 'PCB') and 'metal' with 'bump'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 11:15
S27	2	("6329610").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/20 10:56
S28	9	((("5811982") or ("5914614") or ("6329827") or ("6722032"))).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/20 11:08

EAST Search History

S29	1	"5177438".PN.	USPAT; USOCR	OR	ON	2005/10/20 10:58
S30	1	"5576630".PN.	USPAT; USOCR	OR	ON	2005/10/20 10:58
S31	4	((("6288905") or ("6376769"))).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/20 11:08
S32	951	@ad<="20040330" and 'flexible' with 'substrate' and 'copper' and 'solder ball' and ('printed circuit board' or 'PCB')	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 11:16
S33	353	@ad<="20040330" and 'flexible' with 'substrate' and 'copper' and 'solder ball' and 'PCB'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 11:16
S34	51	@ad<="20040330" and 'wiring substrate' and 'copper' and 'solder ball' and 'PCB'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 11:25
S35	233	@ad<="20040330" and 'wiring board' and 'copper' and 'solder ball' and 'PCB'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 11:17
S36	4	@ad<="20040330" and 'wiring tape' and 'copper' and 'solder ball' and 'PCB'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 11:17
S37	0	@ad<="20040330" and 'fixibel' same 'substrate' and 'copper' with 'pillar' and 'solder ball' and 'PCB'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 11:25
S38	0	@ad<="20040330" and 'fixibel' same 'substrate' and 'copper' and 'solder ball' and 'PCB'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 11:25
S39	0	@ad<="20040330" and 'flexible' same 'substrate' and 'copper' with 'pillar' and 'solder ball' and 'PCB'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 11:26

EAST Search History

S40	425	@ad<="20040330" and 'flexible' same 'substrate' and 'copper' and 'solder ball' and 'PCB'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 11:28
S41	6	@ad<="20040330" and 'flexible' same 'substrate' and 'copper' same 'pillar' and 'solder ball' and 'PCB'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 11:26
S42	105	@ad<="20040330" and 'flexible' same 'substrate' and 'copper' same 'bump' and 'solder ball' and 'PCB'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 11:57
S43	5	@ad<="20040330" and 'flexible' same 'substrate' and 'copper' with 'stud' and 'solder ball' and 'PCB'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 11:28
S44	1	"6010769".PN.	USPAT; USOCR	OR	ON	2005/10/20 11:36
S45	1	"5876842".PN.	USPAT; USOCR	OR	ON	2005/10/20 11:39
S46	1	"5744758".PN.	USPAT; USOCR	OR	ON	2005/10/20 11:39
S47	1	"5600103".PN.	USPAT; USOCR	OR	ON	2005/10/20 11:40
S48	1	"5510216".PN.	USPAT; USOCR	OR	ON	2005/10/20 11:40
S49	67	@ad<="20040330" and 'tape' same 'interposer' and 'copper' and 'solder ball' and 'PCB'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 12:12
S50	2	("6081026").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/20 12:06
S51	1	"5854534".PN.	USPAT; USOCR	OR	ON	2005/10/20 12:09
S52	96	@ad<="20040330" and 'flexible' same 'interposer' and 'copper' and 'solder ball' and 'PCB'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 12:12
S53	80	@ad<="20040330" and 'flexible' with 'interposer' and 'copper' and 'solder ball' and 'PCB'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 12:12

EAST Search History

S54	2	@ad<="20040330" and "wiring substrate" same "solder ball" same "PCB"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/23 11:39
S55	1267	@ad<="20040330" and "wiring substrate" same ("solder ball" or "bump")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/23 11:39
S56	13	@ad<="20040330" and "wiring substrate" same ("bump") same "plug"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/23 11:41
S57	1032	@ad<="20040330" and "wiring substrate" same "bump"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/23 11:41
S59	1234	@ad<="20040330" and "wiring board" same "solder bump"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/23 11:41
S60	246	@ad<="20040330" and "wiring board" with "bump" same "copper"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/23 11:45
S61	101	@ad<="20040330" and "wiring circuit board" with "bump"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/23 11:50
S62	2	@ad<="20040330" and "wiring circuit board" and "plug" with "solder ball"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/23 11:51
S63	16	@ad<="20040330" and "wiring circuit board" and "metal" with "solder ball"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/23 11:51
S64	30	@ad<="20040330" and "wiring circuit board" and "bump" with "solder ball"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/23 11:51